Laser Bonder

Wire bonding is the leading technology to attach electrical contacts to semiconductor components. Not unlike a sewing machine, a wire bonder draws a wire from the semiconductor to the housing and welds it at both ends. This process is fast, reliable and extremely flexible. But there is a limit to the currents which can be passed. Laser welding, on the other hand, can attach wiring of almost any cross-section, but it requires pre-fabricated connector elements, making it less flexible. Why not take the best of both worlds and develop a Laser Bonder which is capable of welding thick wires to connect two points?

Statement of Dr. Farhad Farassat, President of the F&K Delvotec Bondtechnik GmbH

“We are very proud to be honored with the Innovation Award of Productronica for our Laser Bonder. This machine was developed in a cooperation with the Fraunhofer Institute for Laser Technology in Aachen which was as successful as it was enjoyable, all in the framework of a publicly funded R&D project. We are already overwhelmed with inquiries from world-wide inquiries about this revolutionary technology.”

Company Profile F&K Delvotec

F&K Delvotec has been a pioneer in wire bonding, the most important technology to connect semiconductor components. A typical “hidden champion” among equipment makers, the company has consistently been involved in many attractive niche markets from the very beginning – the latest example being batteries for e-vehicles. F&K Delvotec is located in the Munich area and develops and builds all its equipment there but exports over 80% worldwide, to practically all important participants in semiconductor and automotive electronics industries. Since 2014, the company has been part of the mid-size Straubing equipment manufacturer Strama-MPS.

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